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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re PATENT APPLICATION of

ATTN: APPLICATION DIVISION

Choung Hyen KIM et al.

Group Art Unit: 2812

Serial No.: 09/605,660

Examiner: Unknown

Filed: June 28, 2000

Attorney Docket No. SEC.736



For: APPARATUS FOR AND METHOD OF HEAT-TREATING A WAFER

REQUEST FOR CORRECTED FILING RECEIPT

Assistant Secretary and Commissioner  
of Patents and Trademarks,  
Application Processing Division's  
Customer Correction Branch  
Washington, D.C. 20231

Sir:


Attached is a copy of the official filing receipt from the PTO in the above  
application for which issuance of a corrected filing receipt is respectfully requested.

Please correct the following data as follows:

Applicant(s) **SUNG II JANG**, KWACHEON-CITY, KOREA, REPUBLIC OF.

Respectfully submitted,

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Dated: October 20, 2000

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TC 2800 MAIL ROOM

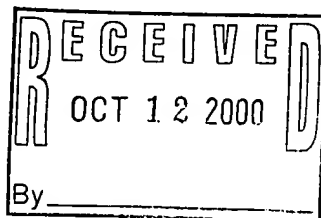


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APPLICATION NUMBER	FILING DATE	GRP ART UNIT	FIL FEE REC'D	ATTY. DOCKET NO.	DRAWINGS	TOT CLAIMS	IND CLAIMS
09/605,660	06/28/2000	2812	690	SEC.736	7	9	2

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## FILING RECEIPT



\*OC000000005446967\*

Date Mailed: 10/03/2000

Receipt is acknowledged of this nonprovisional Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please write to the Office of Initial Patent Examination's Customer Service Center. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the PTO processes the reply to the Notice, the PTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).

## Applicant(s)

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## Continuing Data as Claimed by Applicant

## Foreign Applications

REPUBLIC OF KOREA 1999-25341 06/29/1999

If Required, Foreign Filing License Granted 08/17/2000

## Title

Apparatus for and method of heat-treating a wafer

## Preliminary Class

438

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